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(54) **METHOD FOR MANUFACTURING
SEMICONDUCTOR PACKAGE STRUCTURE**

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(57) **ABSTRACT**

A method for manufacturing a semiconductor package structure is provided. The method includes: (a) providing a semiconductor structure including a first device and a second device; (b) irradiating the first device by a first energy-beam with a first irradiation area; and (c) irradiating the first device and the second device by a second energy-beam with a second irradiation area greater than the first irradiation area of the first energy-beam.

